

MFC

<i>Notice of References Cited</i>		Application No.	Applicant(s)
		09/731,726	Shimizu et al
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		S. Ito	Page 1 of 1

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*	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
A	6160224	12/12/00	Ogashizawa et al	174	257
B					
C					
D					
E					
F					
G					
H					
I	:				
J					
K					
L					
M					

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N	2000015476	1/18/00	JP	Matsumoto et al	-	-
O	115725	4/30/81	PL	Kozlowski et al	-	-
P	409260427	10/3/97	JP	Akamatsu et al	-	-
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NON-PATENT DOCUMENTS

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* A copy of this reference is not being furnished with this Office action.
(See Manual of Patent Examining Procedure, Section 707.05(a).)

Part of Paper No. 3